

CORFIL® 658

Epoxy; Epoxide

Cytec Industries Inc.

Message:

CORFIL 658 is a one-part epoxy material designed for use in insert or edge filling of honeycomb structure. The low viscosity of CORFIL 658 makes it especially suitable for automated or hand filling of small cell sized honeycomb. The thixotropic nature of CORFIL 658 ensures that there is no slump or resin separation during cure. CORFIL 658 is shipped frozen in sealed metal pails or plastic tubes packed with dry ice or by refrigerated carrier.

FEATURES & BENEFITS

Excellent spreadability and extrudability

Compatible with most 350°F (177°C) curing epoxy prepregs

Good compressive strength

SUGGESTED APPLICATIONS

Filling of honeycomb core in sandwich structures, especially in co-bond or co-cure applications

General Information		
Features	Good Compressive Strength	
	Thixotropic	
Uses	Adhesives	
	Filling Applications	
	Structural Parts	
Appearance	White	
Forms	Paste	
Processing Method	Extrusion	
	Potting	
Physical	Nominal Value	Unit
Specific Gravity	0.650 to 0.750	g/cm ³
Mechanical	Nominal Value	Unit
Compressive Strength (24°C)	44.8	MPa
Additional Information	Nominal Value	Unit
Volatiles	< 1.0	%

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Recommended distributors for this material

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